



40V P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	RDS(ON) Max	I _D T _A = +25°C
-40V	11mΩ @ V _{GS} = -10V	-10.8A
	15mΩ @ V _{GS} = -4.5V	-9.6A

Features and Benefits

- 100% Unclamped Inductive Switch (UIS) Test in Production
- Low On-Resistance
- Low Input Capacitance
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative.

https://www.diodes.com/quality/product-definitions/

Description and Applications

This new generation MOSFET has been designed to minimize the onstate resistance (R_{DS(ON)}) yet maintain superior switching performance, making it ideal for high-efficiency power-management applications.

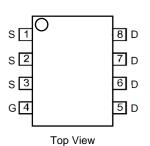
- DC-DC converters
- Power-management functions
- Analog switches

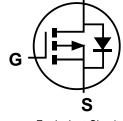
Mechanical Data

- Package: SO-8
- Package Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Lead Frame. Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.074 grams (Approximate)



Top View





Equivalent Circuit

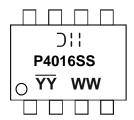
Ordering Information (Note 4)

Part Number	Package	Packing		
	Раскаде	Qty.	Carrier	
DMP4016SSS-13	SO-8	2,500	Tape & Reel	

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



⊃'|| = Manufacturer's Marking
 P4016SS = Product Type Marking Code
 \(\overline{YY}\)WW = Date Code Marking
 \(\overline{YY}\) = Year (ex: 23 = 2023)
 WW = Week (01 to 53)



Maximum Ratings (@ $T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage	VDSS	-40	V		
Gate-Source Voltage	V _{GSS}	±20	V		
Continuous Drain Current (Note 6) V _{GS} = -10V	ID	-10.8 -8.6	А		
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%	IDM	-112	Α		
Maximum Body Diode Continuous Current (Note 6)			Is	-10.8	Α
Avalanche Current, L = 1mH	las	-26	Α		
Avalanche Energy, L = 1mH			Eas	338	mJ

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 5)	PD	1.6	W
Thermal Resistance, Junction to Ambient (Note 5)	R _{θJA}	80.2	°C/W
Total Power Dissipation (Note 6)	PD	2.1	W
Thermal Resistance, Junction to Ambient (Note 6)	R _θ JA	60.4	°C/W
Thermal Resistance, Junction to Case (Note 6)	R _{θJC}	7.8	°C/W
Operating and Storage Temperature Range	TJ, TSTG	-55 to +150	°C

Electrical Characteristics (@ T_A = +25°C, unless otherwise specified.)

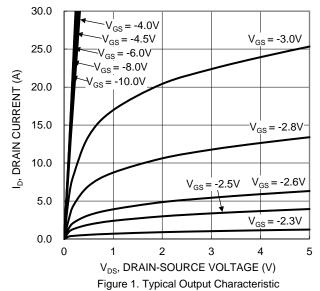
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV _{DSS}	-40		_	V	$V_{GS} = 0V, I_D = -250\mu A$	
Zero Gate Voltage Drain Current	IDSS		_	-1	μA	V _{DS} = -40V, V _{GS} = 0V	
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	Vgs(th)	-1.5	_	-2.5	V	$V_{DS} = V_{GS}$, $I_D = -250\mu A$	
Static Drain-Source On-Resistance	Process	_	6	11	mΩ	$V_{GS} = -10V, I_D = -9.8A$	
Static Dialit-Source Off-Resistance	RDS(ON)	_	8.5	15	11122	$V_{GS} = -4.5V$, $I_{D} = -9.8A$	
Diode Forward Voltage	VsD		-0.7	-1	V	V _G S = 0V, I _S = -1A	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	Ciss		5697				
Output Capacitance	Coss		534		pF	$V_{DS} = -20V$, $V_{GS} = 0V$ f = 1MHz	
Reverse Transfer Capacitance	Crss		408				
Gate Resistance	Rg		7		Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge (V _{GS} = -4.5V)	Qg		53				
Total Gate Charge (V _{GS} = -10V)	Q_g	_	112	_	nC	V _{DS} = -20V. I _D = -9.8A	
Gate-Source Charge	Qgs	_	20	_	IIC	VDS = -20V, ID = -9.6A	
Gate-Drain Charge	Q_{gd}	_	18	_			
Turn-On Delay Time	t _{D(ON)}	_	11.5	_			
Turn-On Rise Time	t _R	_	41	_		$V_{GS} = -10V, V_{DD} = -20V,$	
Turn-Off Delay Time	tD(OFF)	_	146	_	ns	$R_G = 2\Omega$, $I_D = -9.8A$	
Turn-Off Fall Time	tF	_	165	_			
Reverse Recovery Time	t _{RR}	_	27	_	ns	I _F = -9.8A, di/dt = -100A/μs	
Reverse Recovery Charge	Q _{RR}	_	22	_	nC	I _F = -9.8A, di/dt = -100A/μs	

- 5. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
- 6. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.
- 7. Short duration pulse test used to minimize self-heating effect.

 8. Guaranteed by design. Not subject to product testing.







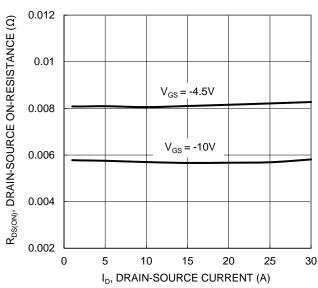


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

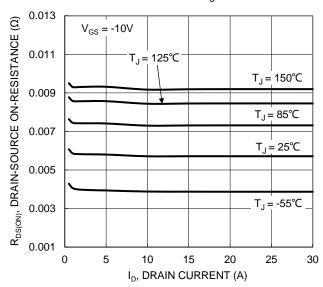


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature

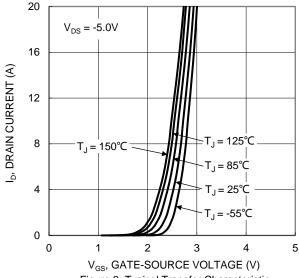


Figure 2. Typical Transfer Characteristic

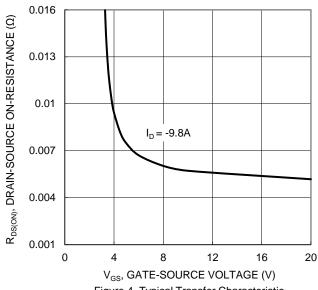


Figure 4. Typical Transfer Characteristic

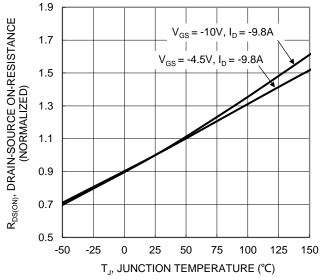


Figure 6. On-Resistance Variation with Junction Temperature





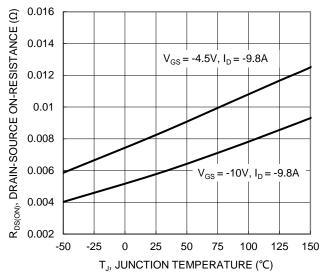


Figure 7. On-Resistance Variation with Junction Temperature

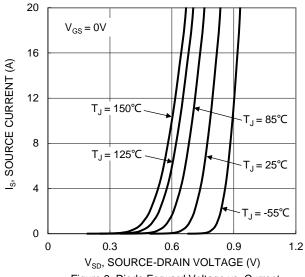


Figure 9. Diode Forward Voltage vs. Current

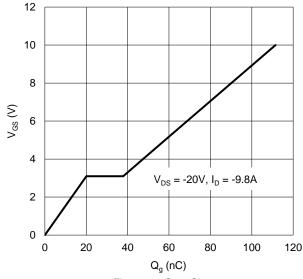


Figure 11. Gate Charge

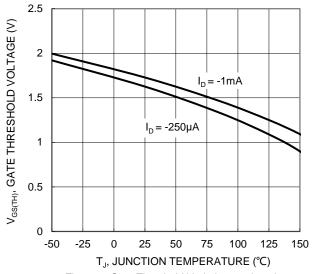


Figure 8. Gate Threshold Variation vs. Junction Temperature

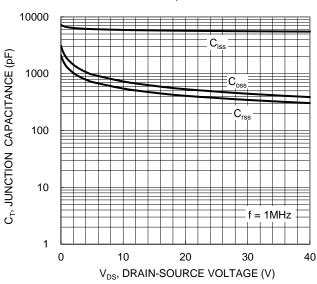


Figure 10. Typical Junction Capacitance

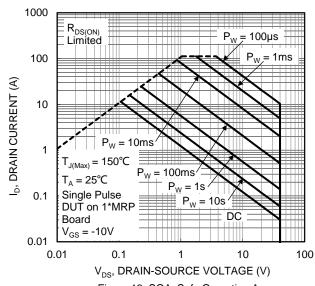


Figure 12. SOA, Safe Operation Area



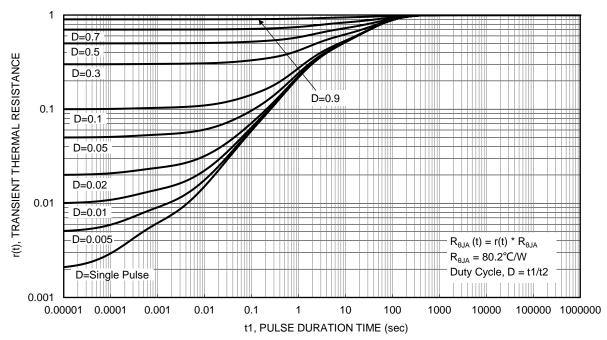
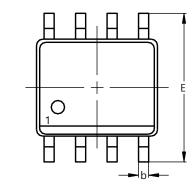


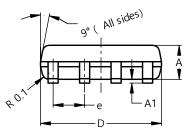
Figure 13. Transient Thermal Resistance

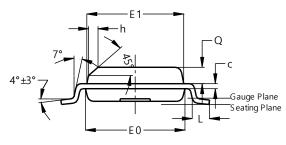


Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.







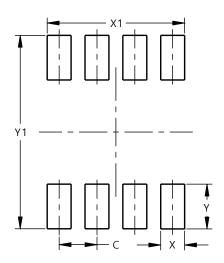
SO-8

SO-8					
Dim	Min	Max	Тур		
Α	1.40	1.50	1.45		
A 1	0.10	0.20	0.15		
b	0.30	0.50	0.40		
С	0.15	0.25	0.20		
D	4.85	4.95	4.90		
Е	5.90	6.10	6.00		
E1	3.80	3.90	3.85		
E0	3.85	3.95	3.90		
е			1.27		
h			0.35		
L	0.62	0.82	0.72		
Q	0.60	0.70	0.65		
All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.





Dimensions	Value (in mm)
С	1.27
Х	0.802
X1	4.612
Υ	1.505
Y1	6.50



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